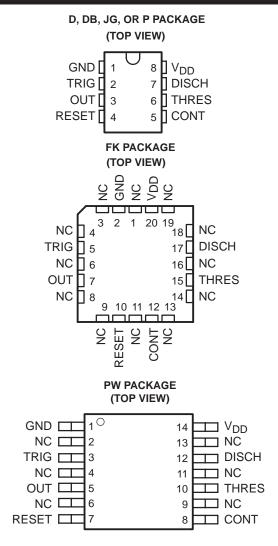
- Very Low Power Consumption

 1 mW Typ at V_{DD} = 5 V
- Capable of Operation in Astable Mode
- CMOS Output Capable of Swinging Rail to Rail
- High Output-Current Capability
 Sink 100 mA Typ
 - Source 10 mA Typ
- Output Fully Compatible With CMOS, TTL, and MOS
- Low Supply Current Reduces Spikes During Output Transitions
- Single-Supply Operation From 2 V to 15 V
- Functionally Interchangeable With the NE555; Has Same Pinout
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015.2
- Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control/Print Support Qualification to Automotive Standards

description

The TLC555 is a monolithic timing circuit fabricated using the TI LinCMOS[™] process. The timer is fully compatible with CMOS, TTL, and MOS logic and operates at frequencies up to 2 MHz. Because of its high input impedance, this device uses smaller timing capacitors than those used by the NE555. As a result, more accurate time delays and oscillations are possible. Power consumption is low across the full range of power supply voltage.



NC - No internal connection

Like the NE555, the TLC555 has a trigger level equal to approximately one-third of the supply voltage and a threshold level equal to approximately two-thirds of the supply voltage. These levels can be altered by use of the control voltage terminal (CONT). When the trigger input (TRIG) falls below the trigger level, the flip-flop is set and the output goes high. If TRIG is above the trigger level and the threshold input (THRES) is above the threshold level, the flip-flop is reset and the output is low. The reset input (RESET) can override all other inputs and can be used to initiate a new timing cycle. If RESET is low, the flip-flop is reset and the output is low. Whenever the output is low, a low-impedance path is provided between the discharge terminal (DISCH) and GND. All unused inputs should be tied to an appropriate logic level to prevent false triggering.

While the CMOS output is capable of sinking over 100 mA and sourcing over 10 mA, the TLC555 exhibits greatly reduced supply-current spikes during output transitions. This minimizes the need for the large decoupling capacitors required by the NE555.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinCMOS is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1983–2005, Texas Instruments Incorporated On products compliant to MIL-PRF-3835, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

description (continued)

The TLC555C is characterized for operation from 0°C to 70°C. The TLC555I is characterized for operation from -40°C to 85°C. The TLC555Q is characterized for operation over the automotive temperature range of -40°C to 125°C. The TLC555M is characterized for operation over the full military temperature range of -55°C to 125°C.

	PACKAGED DEVICES											
TA	V _{DD} RANGE	SMALL OUTLINE (D) [‡]	SSOP (DB) [‡]	CHIP CARRIER (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)	TSSOP (PW) [‡]					
0°C to 70°C	2 V to 15 V	TLC555CD	TLC555CDB	—	_	TLC555CP	TLC555CPW					
-40°C to 85°C	3 V to 15 V	TLC555ID	_	—	_	TLC555IP	_					
-40°C to 125°C	5 V to 15 V	TLC555QD		—	_	_						
–55°C to 125°C	5 V to 15 V	TLC555MD	_	TLC555MFK	TLC555MJG	TLC555MP	_					

AVAILABLE OPTIONS †

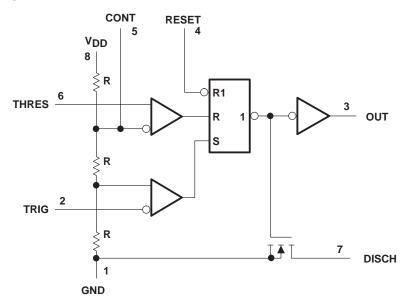
[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

[‡]This package is available taped and reeled. Add the R suffix to device type (e.g., TLC555CDR).

FUNCTION TABLE RESET VOLTAGE[‡] TRIGGER VOLTAGE[‡] THRESHOLD VOLTAGE[‡] OUTPUT **DISCHARGE SWITCH** <MIN Irrelevant Irrelevant L On Off >MAX <MIN Н Irrelevant >MAX >MAX >MAX L On >MAX >MAX <MIN As previously established

[‡]For conditions shown as MIN or MAX, use the appropriate value specified under electrical characteristics.

functional block diagram

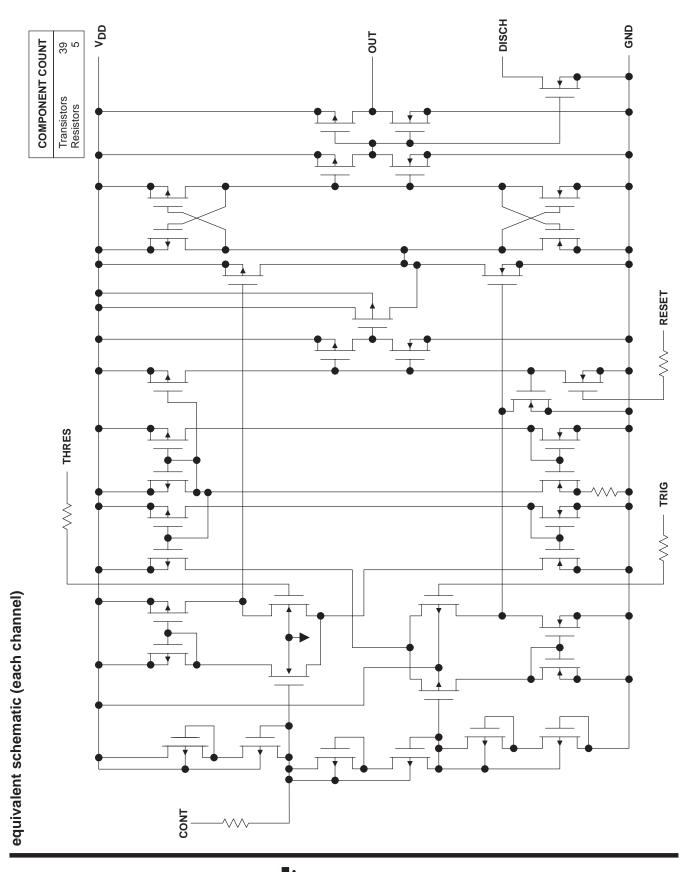


Pin numbers are for all packages except the FK package. RESET can override TRIG, which can override THRES.



TLC555 LinCMOS™ TIMER

SLFS043F - SEPTEMBER 1983 - REVISED FEBRUARY 2005





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{DD} (see Note 1) Input voltage range, V _I (any input) Sink current, discharge or output		–0.3 to V _{DD} 150 mA
Source current, output, IO		
Continuous total power dissipation		. See Dissipation Rating Table
Operating free-air temperature range, T_A :	C-suffix	0°C to 70°C
	I-suffix	–40°C to 85°C
	Q-suffix	–40°C to 125°C
	M-suffix	–55°C to 125°C
Storage temperature range		–65°C to 150°C
Case temperature for 60 seconds: FK pack	kage	260°C
Lead temperature 1,6 mm (1/16 inch) from Lead temperature 1,6 mm (1/16 inch) from	n case for 60 seconds: JG package	e 300°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network GND.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
DB	525 mW	4.2 mW/°C	336 mW	273 mW	105 mW
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
Р	1000 mW	8.0 mW/°C	640 mW	520 mW	200 mW
PW	525 mW	4.2 mW/°C	336 mW	273 mW	105 mW

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, VDD		2	15	V
	TLC555C	0	70	
	TLC555I	-40	85	°C
Operating free-air temperature range, T _A	TLC555Q	-40	125	
	TLC555M	-55	125	



electrical characteristics at specified free-air temperature,	$V_{DD} = 2 V$ for TLC555C, $V_{DD} = 3 V$ for
TLC555I	

		TEST	_ +	1	LC555C		-	TLC555I			
	PARAMETER	CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
			25°C	0.95	1.33	1.65	1.6		2.4		
VIT	Threshold voltage		Full range	0.85		1.75	1.5		2.5	V	
	-		25°C		10			10			
lιτ	Threshold current		MAX		75			150		pА	
.,			25°C	0.4	0.67	0.95	0.71	1	1.29		
VI(TRIG)	Trigger voltage		Full range	0.3		1.05	0.61		1.39	V	
			25°C		10			10			
l(TRIG)	Trigger current	MAX 75 150			pА						
.,	-		25°C	0.4	1.1	1.5	0.4	1.1	1.5		
VI(RESET)	Reset voltage		Full range	0.3		2	0.3		1.8	V	
			25°C		10			10			
II(RESET)	Reset current		MAX		75			150		рА	
	Control voltage (open circuit) as a percentage of supply voltage		MAX		66.7%			66.7%			
	Discharge switch on-stage		25°C		0.03	0.2		0.03	0.2		
	voltage	I _{OL} = 1 mA	Full range			0.25			0.375	V	
	Discharge switch off-stage		25°C		0.1			0.1			
	current		MAX		0.5			120		nA	
			25°C	1.5	1.9		2.5	2.85		.,	
VOH	High-level output voltage	I _{OH} = -300 μA	Full range	1.5			2.5			V	
			25°C		0.07	0.3		0.07	0.3		
VOL	Low-level output voltage	I _{OL} = 1 mA	Full range			0.35			0.4	V	
1	Supply automat	See Note 2	25°C	°C 250			250	A			
DD	Supply current	See Note 2	Full range			400			500	μΑ	

[†] Full range is 0°C to 70°C for the TLC555C and -40°C to 85°C for the TLC555I. For conditions shown as MAX, use the appropriate value specified in the recommended operating conditions table.

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or to TRIG.



electrical characteristics at specified free-air temperature, V_{DD} = 5 V

		TEST	- +	٦	LC555C		-	FLC555I		TLC55	5Q, TLC	555M	
I	PARAMETER	CONDITIONS	TA‡	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
.,			25°C	2.8	3.3	3.8	2.8	3.3	3.8	2.8	3.3	3.8	
VIT	Threshold voltage		Full range	2.7		3.9	2.7		3.9	2.7		3.9	V
	-		25°C		10			10			10		
ΊΤ	Threshold current		MAX		75			150			5000		pА
	T :		25°C	1.36	1.66	1.96	1.36	1.66	1.96	1.36	1.66	1.96	
VI(TRIG)	Trigger voltage		Full range	1.26		2.06	1.26		2.06	1.26		2.06	V
	T :		25°C		10			10			10		
l(trig)	Trigger current		MAX		75			150			5000		pА
	D		25°C	0.4	1.1	1.5	0.4	1.1	1.5	0.4	1.1	1.5	
VI(RESET)	Reset voltage		Full range	0.3		1.8	0.3		1.8	0.3		1.8	V
			25°C		10			10			10		
I(RESET)	Reset current		MAX		75			150			5000		pА
	Control voltage (open circuit) as a percent- age of supply voltage		MAX		66.7%			66.7%			66.7%		
	Discharge switch		25°C		0.14	0.5		0.14	0.5		0.14	0.5	
	on-state voltage	I _{OL} = 10 mA	Full range			0.6			0.6			0.6	V
	Discharge switch		25°C		0.1			0.1			0.1		
	off-state current		MAX		0.5			120			120		nA
.,	High-level output		25°C	4.1	4.8		4.1	4.8		4.1	4.8		
VOH	voltage	$I_{OH} = -1 \text{ mA}$	Full range	4.1			4.1			4.1			V
			25°C		0.21	0.4		0.21	0.4		0.21	0.4	
		1 _{OL} = 8 mA	Full range			0.5			0.5			0.6	
	Low-level output		25°C		0.13	0.3		0.13	0.3		0.13	0.3	
V _{OL}	voltage	I _{OL} = 5 mA	Full range			0.4			0.4			0.45	V
		1	25°C		0.08	0.3		0.08	0.3		0.08	0.3	
		I _{OL} = 3.2 mA	Full range			0.35			0.35			0.4	
1	Supply surrent	ent See Note 2	25°C		170	350		170	350		170	350	
IDD	Supply current		Full range			500			600			700	μA

[†] Full range is 0°C to 70°C the for TLC555C, -40°C to 85°C for the TLC555I, -40°C to 125°C for the TLC555Q, and -55°C to 125°C for the TLC555M. For conditions shown as MAX, use the appropriate value specified in the recommended operating conditions table. NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.



_		TEST	_ +	-	TLC555C		-	FLC555I		TLC55	5Q, TLC	555M	
P	ARAMETER	CONDITIONS	τ _A †	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	There is a list worker and		25°C	9.45	10	10.55	9.45	10	10.55	9.45	10	10.55	V
VIT	Threshold voltage		Full range	9.35		10.65	9.35		10.65	9.35		10.65	V
	T I		25°C		10			10			10		
IТ	Threshold current		MAX		75			150			5000		рA
	Trianauthana		25°C	4.65	5	5.35	4.65	5	5.35	4.65	5	5.35	v
VI(TRIG)	Trigger voltage		Full range	4.55		5.45	4.55		5.45	4.55		5.45	V
I	Trigger oursent		25°C		10			10			10		рА
li(TRIG)	G) Trigger current		MAX		75			150			5000		
	Depart voltage		25°C	0.4	1.1	1.5	0.4	1.1	1.5	0.4	1.1	1.5	v
VI(RESET)	SET) Reset voltage		Full range	0.3		1.8	0.3		1.8	0.3		1.8	V
	Reset current		25°C		10			10			10		- 4
I(RESET)	Reset current		MAX		75			150			5000		рA
	Control voltage (open circuit) as a percent- age of supply voltage		MAX		66.7%			66.7%			66.7%		
	Discharge switch	I _{OL} = 100 mA	25°C		0.77	1.7		0.77	1.7		0.77	1.7	
	on-state voltage		Full range			1.8			1.8			1.8	V
	Discharge switch off-state current	1	25°C		0.1			0.1			0.1		- 1
			MAX		0.5			120			120		nA
		10 mA	25°C	12.5	14.2		12.5	14.2		12.5	14.2		
		I _{OH} = - 10 mA	Full range	12.5			12.5			12.5			
V	High-level output	lau - EmA	25°C	13.5	14.6		13.5	14.6		13.5	14.6		v
Vон	voltage	I _{OH} = - 5 mA	Full range	13.5			13.5			13.5			v
		1	25°C	14.2	14.9		14.2	14.9		14.2	14.9		
		I _{OH} = - 1 mA	Full range	14.2			14.2			14.2			
		I _{OL} = 100 mA	25°C		1.28	3.2		1.28	3.2		1.28	3.2	
		OC = 100 mA	Full range			3.6			3.7			3.8	
1.	Low-level output	la: 50 mA	25°C		0.63	1		0.63	1		0.63	1	
VOL	voltage	IOL = 50 mA	Full range			1.3			1.4			1.5	V
		10 - 10 - 10	25°C		0.12	0.3		0.12	0.3		0.12	0.3	
	١c	I _{OL} = 10 mA	Full range			0.4			0.4			0.45	
I	Supply ourset	Can Nata O	25°C		360	600		360	600		360	600	
IDD	Supply current	See Note 2	Full range			800			900			1000	μA

[†] Full range is 0°C to 70°C for TLC555C, -40°C to 85°C for TLC555I, -40°C to 125°C for the TLC555Q, and -55°C to 125°C for TLC555M. For conditions shown as MAX, use the appropriate value specified in the recommended operating conditions table.

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.



operating characteristics, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
	Initial error of timing interval [‡]	$V_{DD} = 5 V \text{ to } 15 V,$	$R_A = R_B = 1 k\Omega$ to 100 kΩ,		1%	3%	
	Supply voltage sensitivity of timing interval	C _T = 0.1 μF,	See Note 3		0.1	0.5	%/V
tr	Output pulse rise time	D 40.140	0 40 - 5		20	75	
t _f	Output pulse fall time	R _L = 10 MΩ,	C _L = 10 pF		15	60	ns
f _{max}	Maximum frequency in astable mode	R _A = 470 Ω, C _T = 200 pF,	R _B = 200 Ω, See Note 3	1.2	2.1		MHz

[‡] Timing interval error is defined as the difference between the measured value and the average value of a random sample from each process run.

NOTE 3: R_A , R_B , and C_T are as defined in Figure 1.

electrical characteristics at V_DD = 5 V, T_A = 25 $^\circ\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IT}	Threshold voltage		2.8	3.3	3.8	V
Ι _{ΙΤ}	Threshold current			10		pА
VI(TRIG)	Trigger voltage		1.36	1.66	1.96	V
l _{I(TRIG)}	Trigger current			10		pА
VI(RESET)	Reset voltage		0.4	1.1	1.5	V
II(RESET)	Reset current			10		pА
	Control voltage (open circuit) as a percentage of supply voltage			66.7%		
	Discharge switch on-state voltage	I _{OL} = 10 mA		0.14	0.5	V
	Discharge switch off-state current			0.1		nA
VOH	High-level output voltage	I _{OH} = - 1 mA	4.1	4.8		V
		I _{OL} = 8 mA		0.21	0.4	
VOL	Low-level output voltage	I _{OL} = 5 mA		0.13	0.3	V
		I _{OL} = 3.2 mA		0.08	0.3	
IDD	Supply current	See Note 2		170	350	μΑ

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.



PROPAGATION DELAY TIMES TO DISCHARGE

TYPICAL CHARACTERISTICS

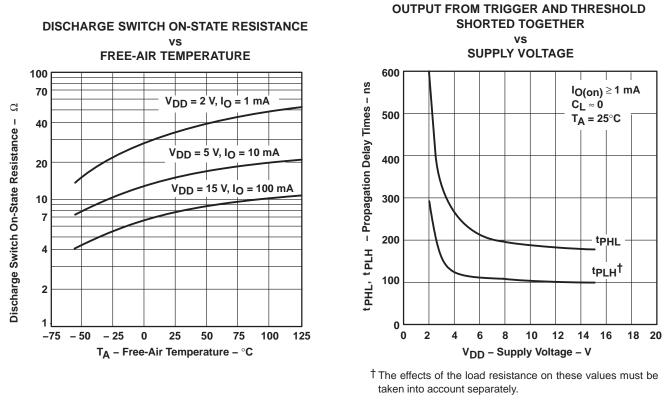
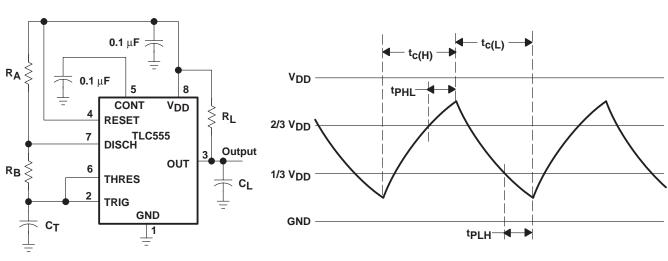


Figure 1





APPLICATION INFORMATION

Pin numbers shown are for all packages except the FK package.

TRIGGER AND THRESHOLD VOLTAGE WAVEFORM

CIRCUIT

Figure 3. Astable Operation



APPLICATION INFORMATION

Connecting TRIG to THRES, as shown in Figure 3, causes the timer to run as a multivibrator. The capacitor C_T charges through R_A and R_B to the threshold voltage level (approximately 0.67 V_{DD}) and then discharges through R_B only to the value of the trigger voltage level (approximately 0.33 V_{DD}). The output is high during the charging cycle ($t_{c(H)}$) and low during the discharge cycle ($t_{c(L)}$). The duty cycle is controlled by the values of R_A , R_B , and C_T as shown in the equations below.

$$\begin{split} t_{c(H)} &\approx C_{T} (R_{A} + R_{B}) \ln 2 \quad (\ln 2 = 0.693) \\ t_{c(L)} &\approx C_{T} R_{B} \ln 2 \\ \text{Period} &= t_{c(H)} + t_{c(L)} \approx C_{T} (R_{A} + 2R_{B}) \ln 2 \\ \text{Output driver duty cycle} &= \frac{t_{c(L)}}{t_{c(H)} + t_{c(L)}} \approx 1 - \frac{R_{B}}{R_{A} + 2R_{B}} \\ \text{Output waveform duty cycle} &= \frac{t_{c(H)}}{t_{c(H)} + t_{c(L)}} \approx \frac{R_{B}}{R_{A} + 2R_{B}} \end{split}$$

The $0.1-\mu$ F capacitor at CONT in Figure 3 decreases the period by about 10%.

The formulas shown above do not allow for any propagation delay times from the TRIG and THRES inputs to DISCH. These delay times add directly to the period and create differences between calculated and actual values that increase with frequency. In addition, the internal on-state resistance r_{on} during discharge adds to R_B to provide another source of timing error in the calculation when R_B is very low or r_{on} is very high.

The equations below provide better agreement with measured values.

$$t_{c(H)} = C_{T}(R_{A} + R_{B}) \ln \left[3 - \exp\left(\frac{-t_{PLH}}{C_{T}(R_{B} + r_{on})}\right) \right] + t_{PHL}$$
$$t_{c(L)} = C_{T}(R_{B} + r_{on}) \ln \left[3 - \exp\left(\frac{-t_{PHL}}{C_{T}(R_{A} + R_{B})}\right) \right] + t_{PLH}$$

These equations and those given earlier are similar in that a time constant is multiplied by the logarithm of a number or function. The limit values of the logarithmic terms must be between In 2 at low frequencies and In 3 at extremely high frequencies. For a duty cycle close to 50%, an appropriate constant for the logarithmic terms can be substituted

with good results. Duty cycles less than 50% $\frac{t_c(H)}{t_c(H) + t_c(L)}$ require that $\frac{t_c(H)}{t_c(L)} < 1$ and possibly $R_A \le r_{on}$. These

conditions can be difficult to obtain.

In monostable applications, the trip point on TRIG can be set by a voltage applied to CONT. An input voltage between 10% and 80% of the supply voltage from a resistor divider with at least $500-\mu$ A bias provides good results.



12-Oct-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-89503012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8950301PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TLC555CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC555CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC555CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC555IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC555IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC555MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TLC555MJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TLC555MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TLC555MP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TLC555QDR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC555QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
 ACTIVE: Product device recommended for new designs.
 LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.





NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

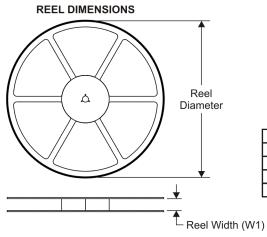
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

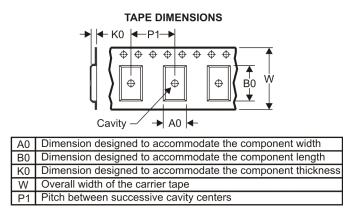
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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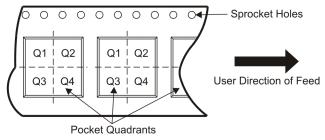
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

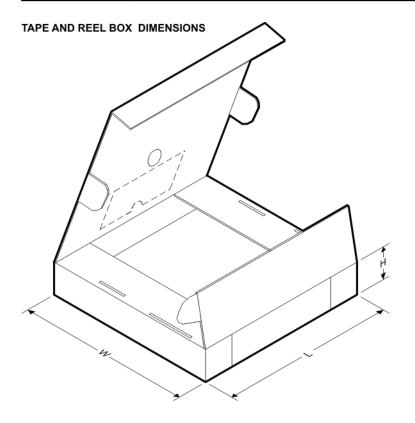


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC555CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC555CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC555CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TLC555CPWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
TLC555IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC555IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008

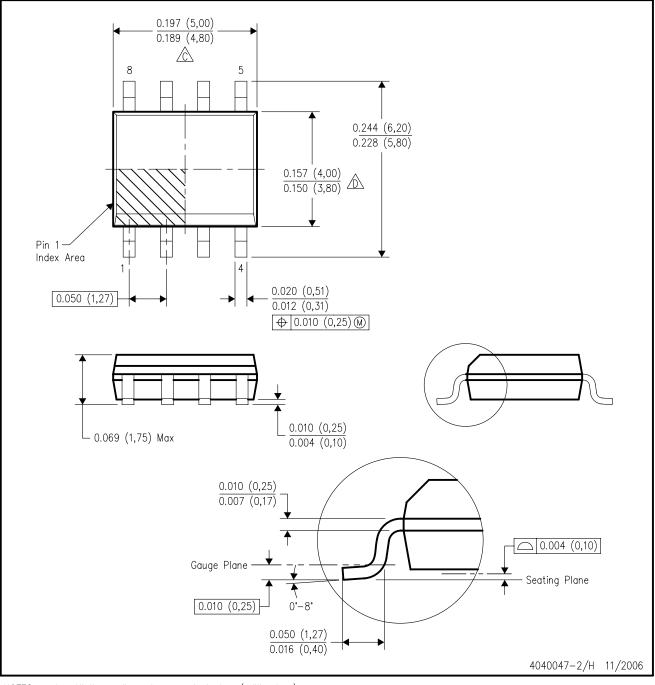


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC555CDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC555CDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC555CPSR	SO	PS	8	2000	346.0	346.0	33.0
TLC555CPWR	TSSOP	PW	14	2000	346.0	346.0	29.0
TLC555IDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC555IDR	SOIC	D	8	2500	346.0	346.0	29.0

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.

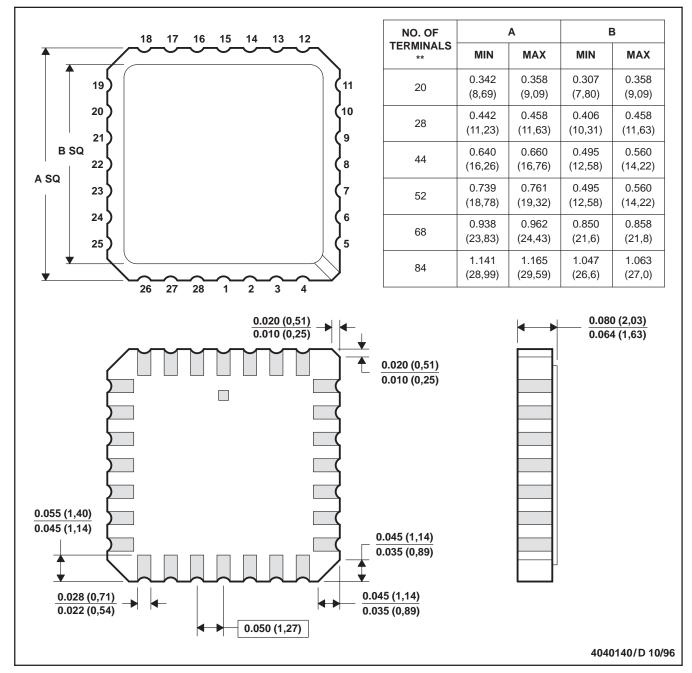


MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



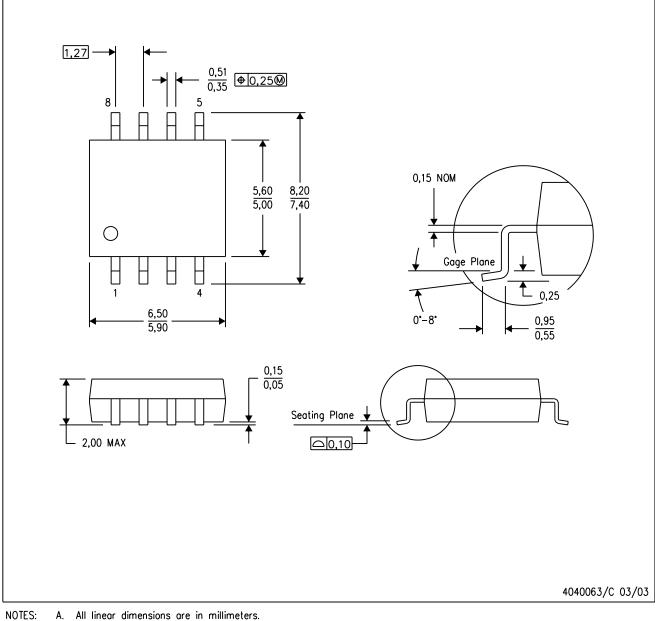
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



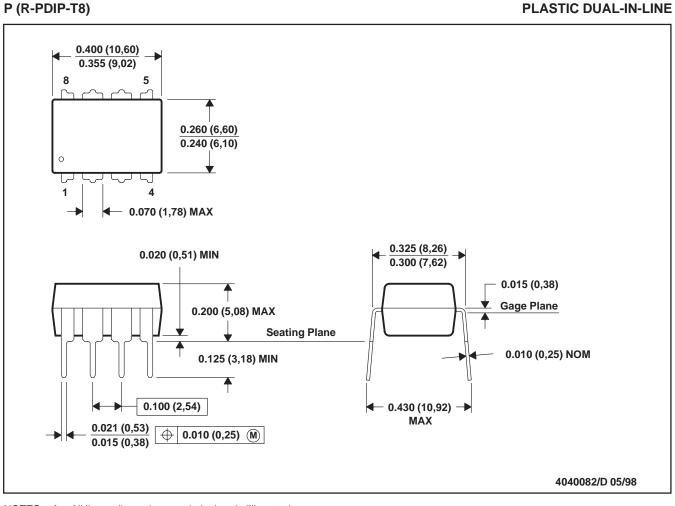
A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MPDI001A - JANUARY 1995 - REVISED JUNE 1999



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001

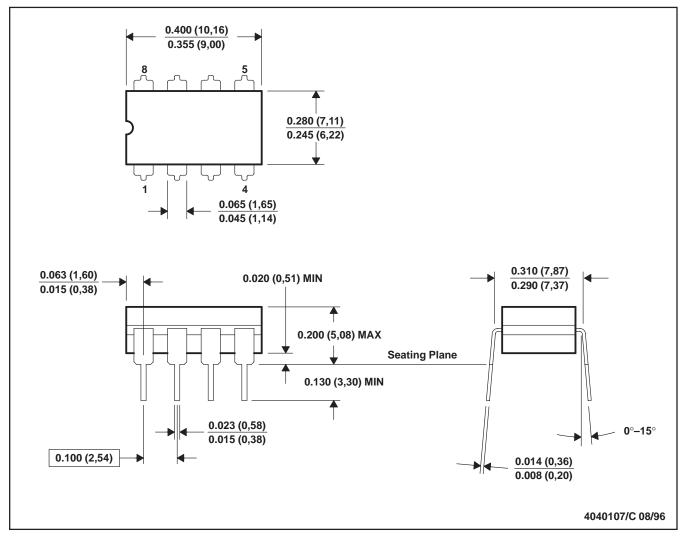
For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



MCER001A - JANUARY 1995 - REVISED JANUARY 1997



CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



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